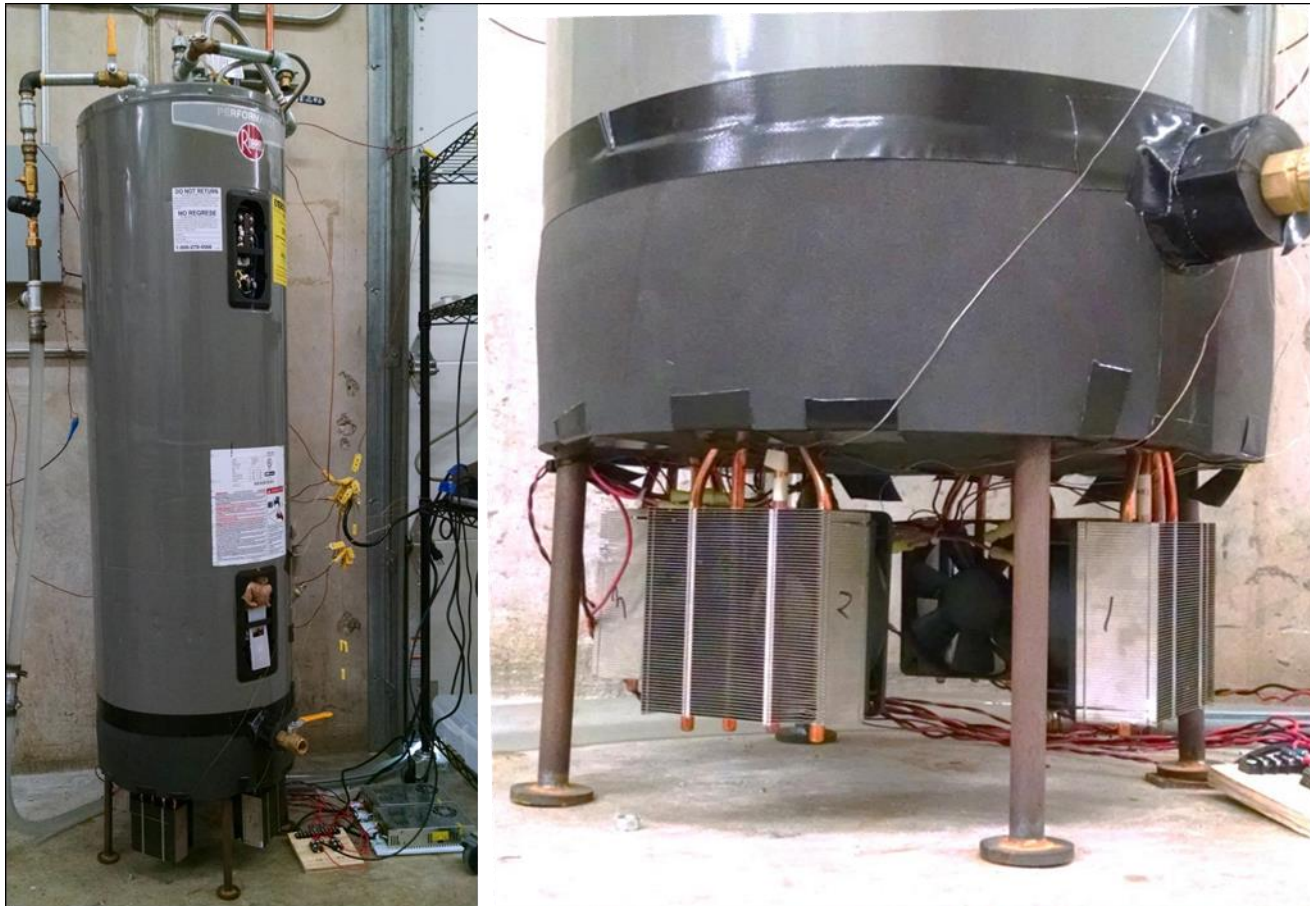


Heat Pump Water Heater Using Solid-State Energy Converters

2015 Building Technologies Office Peer Review



Project Summary

Timeline:

Start date: 11/15/2012

Planned end date: 5/14/2016

Key Milestones:

1. Development of Bottom Mount 4-Engine Thermoelectric Heat Pump; 5/14/2014
2. Development of High Cooling Power Thermoelectric Modules for Heat Pumps; 5/14/2015
3. Performance (COP > 1.1) and Reliability of 4- and 8-Engine Thermoelectric Heat Pumps ; 6/14/2016

Budget:

Total DOE \$ to date: \$1149900.00

Total future DOE \$: \$499975.00

Target Market/Audience:

Home Water Heaters with Affordable, Reliable Solid-State Heat Pumps

Key Partners:

Whirlpool Appliance (Consultation for Specs)

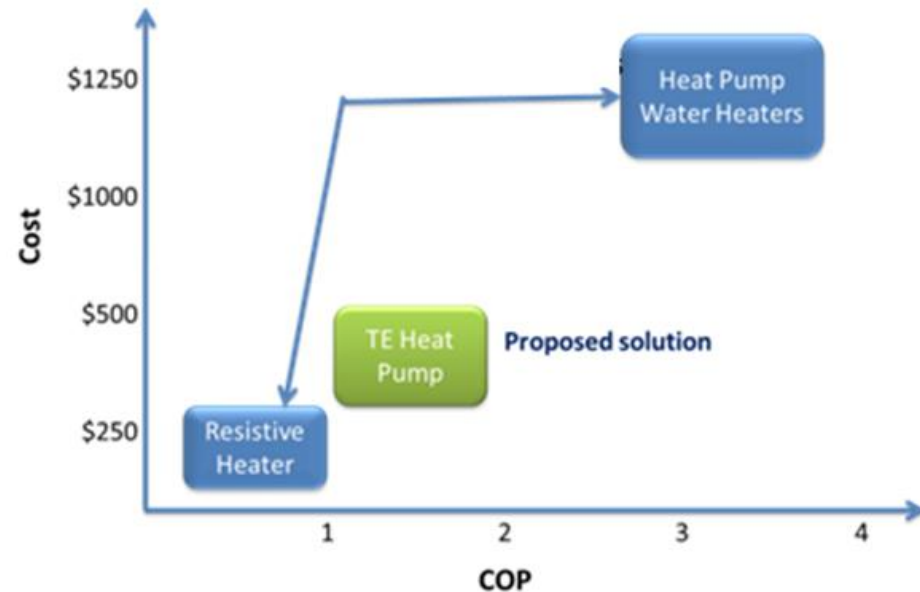
Project Goal:

Demonstrate a home water heater product with affordable and reliable solid-state heat pumps with COP > 1.1 The project includes development of high cooling power thermoelectric modules as well as development of bottom-mount 4-engine and 8-engine heat pumps.

Purpose and Objectives

Residential Water Heaters

- 15% of energy consumption
- 45% are electric heaters: ~ 1.34 Quads of primary energy
- \$300- \$700 per year energy cost
- Vapor compression based heat pump water heater are very expensive



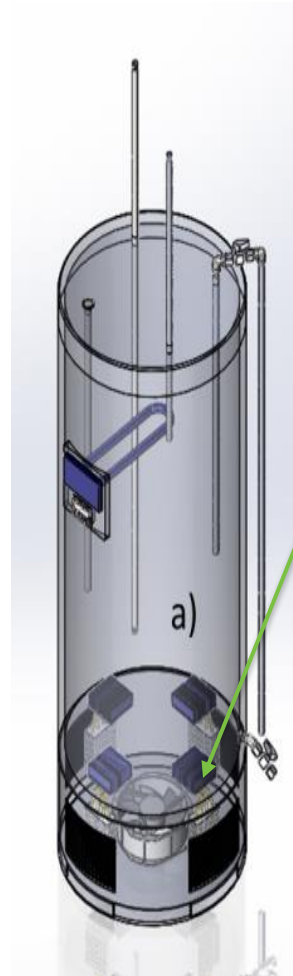
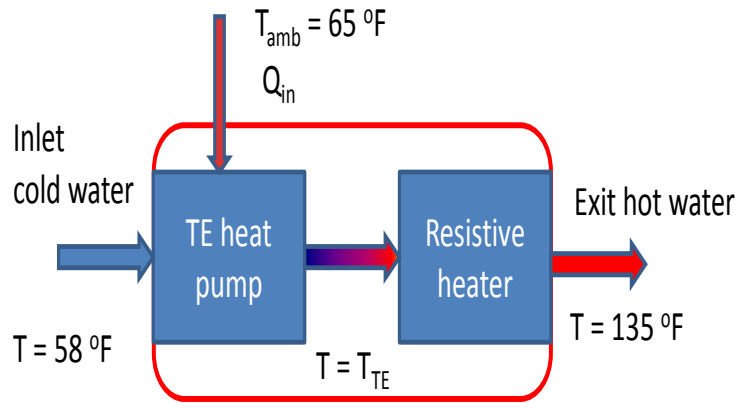
Sheetak's Solution

Low-Cost Thermoelectric (TE) Heat Pump Water Heater

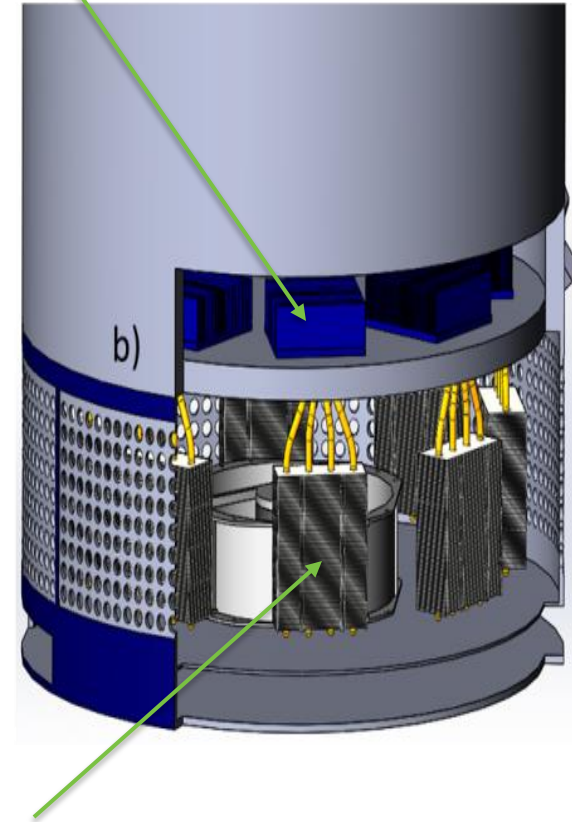
Impact of the Project

- Demonstration of first TE-based 50 gallon heat pump water heater
- COP > 1.1 (goal of the SBIR)
- Development of novel thermoelectric modules and substrates
- Development of novel system-level hardware
- Cost-effective heat pump water heater
- Achievements
 - Near term: COP > 1 with 4 TE cooling engines
 - Intermediate term: COP > 1.2 with 8 TE cooling engines, teaming with a water heater manufacturer
 - Long term: Launch of TE based water heater in the market

Thermoelectric Heat Pump Water Heater

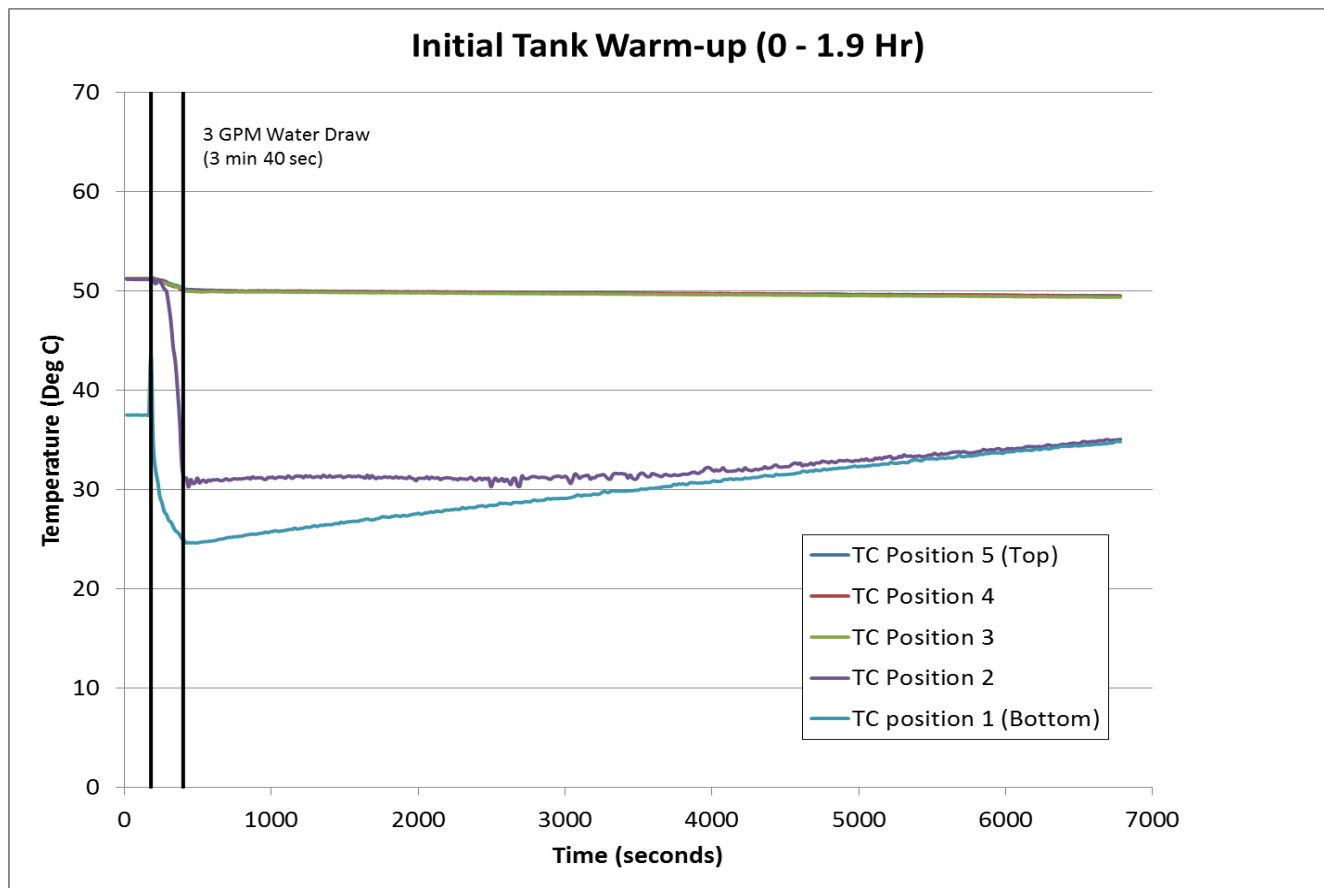


Thermoelectric Hot Side



Thermoelectric Cold Side (Heat-Pipe Heat Sink)

Preliminary Results: 4 TE Engine Water Heater

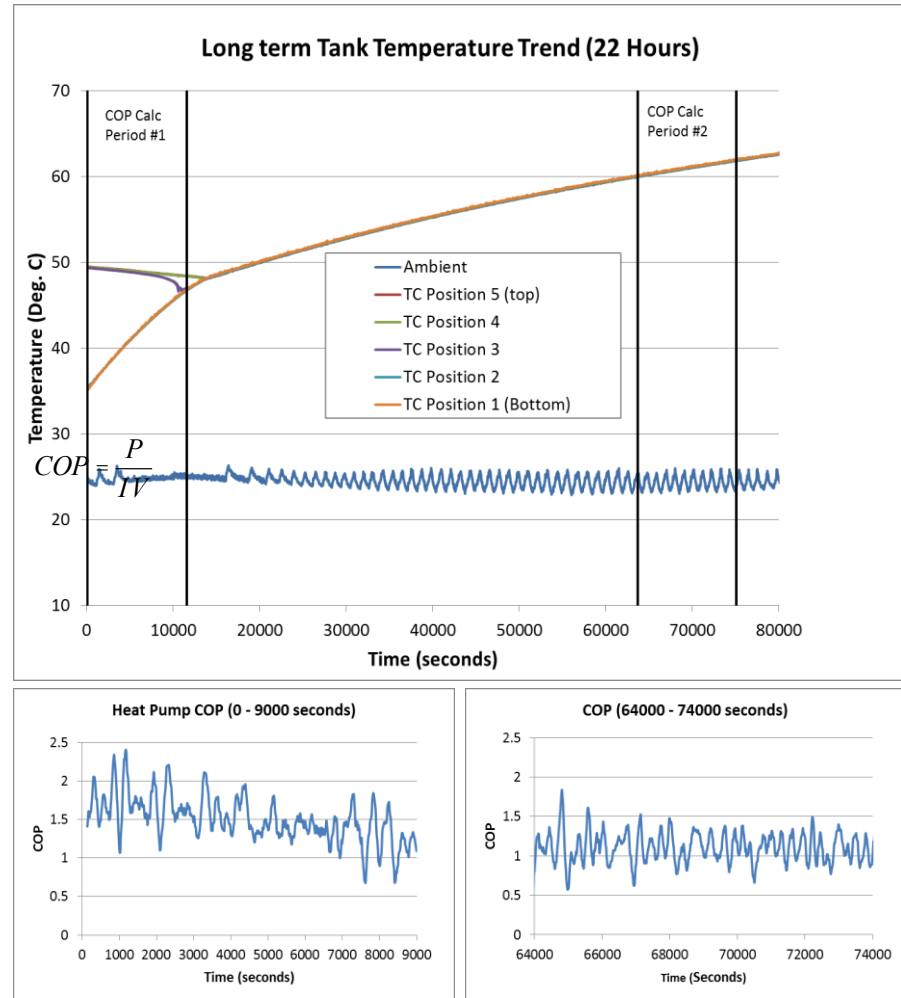


- 3GPM water withdrawal in 3 minutes 40 sec (as per testing standards)
- Only TE used for heating after the withdrawal
- Issues: Slow heating observed by TE

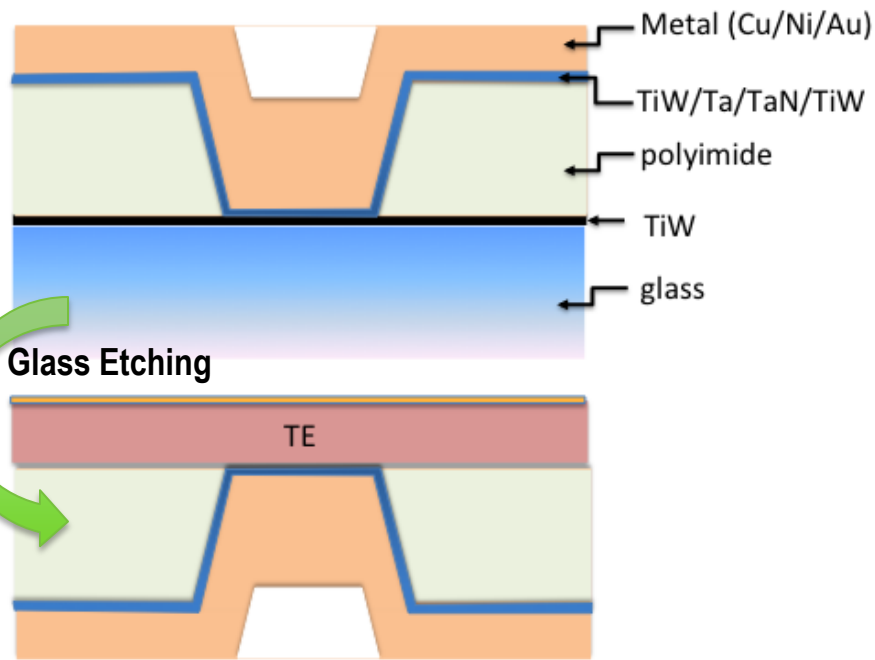
Preliminary Results: 4 TE Engine Water Heater

$$P = mC_p \frac{dT}{dt} + K(T - T_a)$$
$$COP = \frac{P}{IV}$$

- P = heating rate, estimated using the above equation
- Due to discrete measurements and fluctuations in ambient temperature, there are some uncertainties
- COP is high in the beginning due to low temperature difference
- COP decreases with time due to increase in temperature difference
- After a certain temperature rise, resistive heater will be switched on (work on controls, in progress)



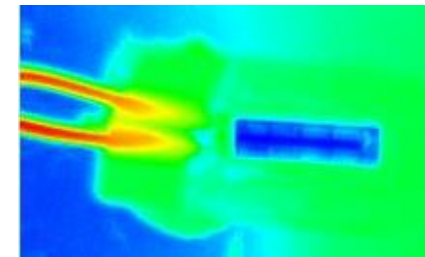
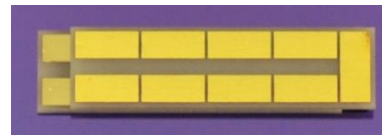
High Performance TE Modules – Thin Film Devices



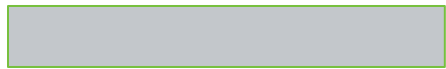
- ❖ Very high heat flux $> 100 \text{ W/cm}^2$
- ❖ $\Delta T \sim 50^\circ\text{C}$ for AlN substrates, COP ~ 0.6 for ΔT (external) = 30°C
- ❖ Requires metal-core substrates and high performance solders
- ❖ Packaging cost may be high

Thin Film $\text{Bi}_{0.5}\text{Sb}_{1.5}\text{Te}_{3.0}$
and $\text{Bi}_2\text{Te}_{2.8}\text{Se}_{0.2}$ Devices

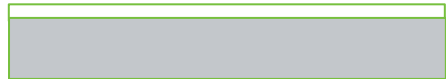
8-Couple Q&T



High Performance TE Modules – Substrates



Al Wafer



ALD Alumina



Copper Seed Layers



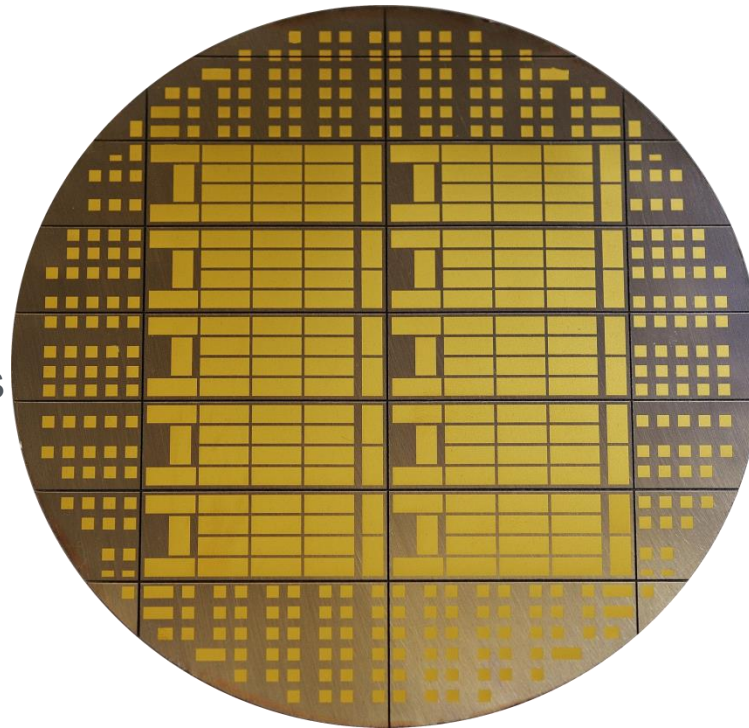
Patterning



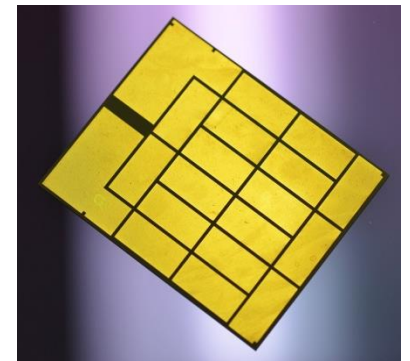
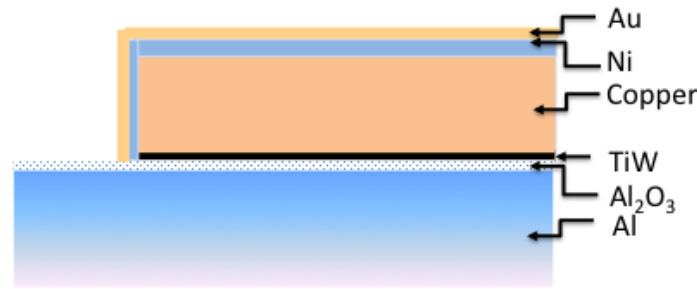
Copper/Ni/Au Plating



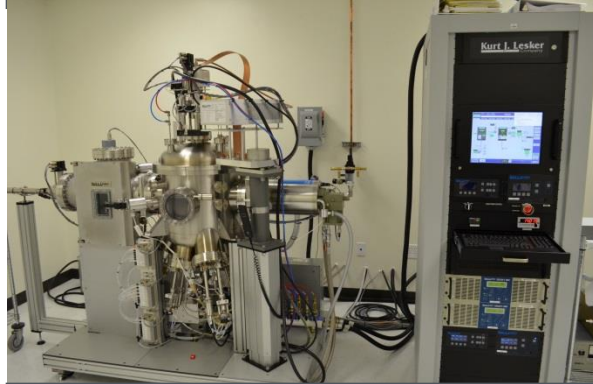
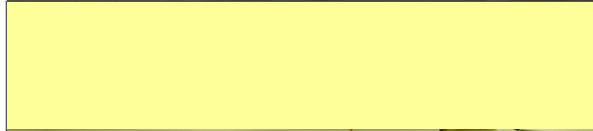
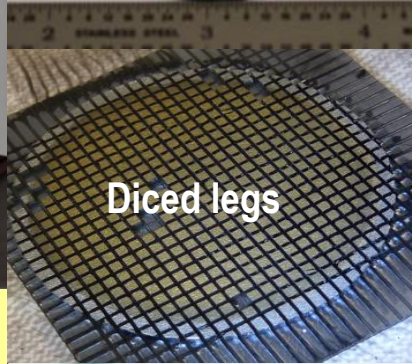
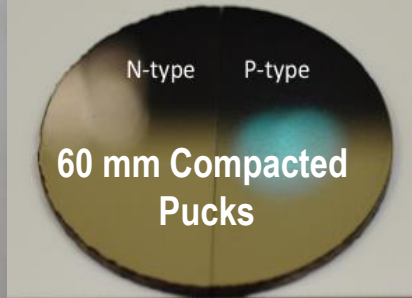
Seed Removal and Dicing



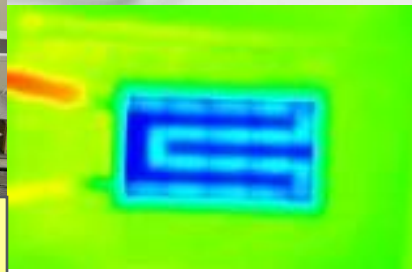
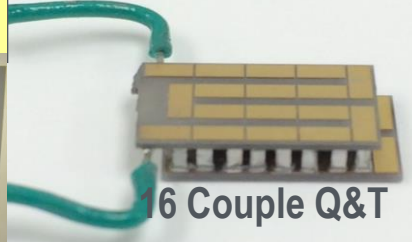
- ❖ 150-200 mm Al wafers
- ❖ ΔT (substrate) $< 1^\circ\text{C}$ for flux $\sim 100\text{W}/\text{cm}^2$
- ❖ Lower cost than AlN ceramics
- ❖ CTE-compatible with heat exchangers



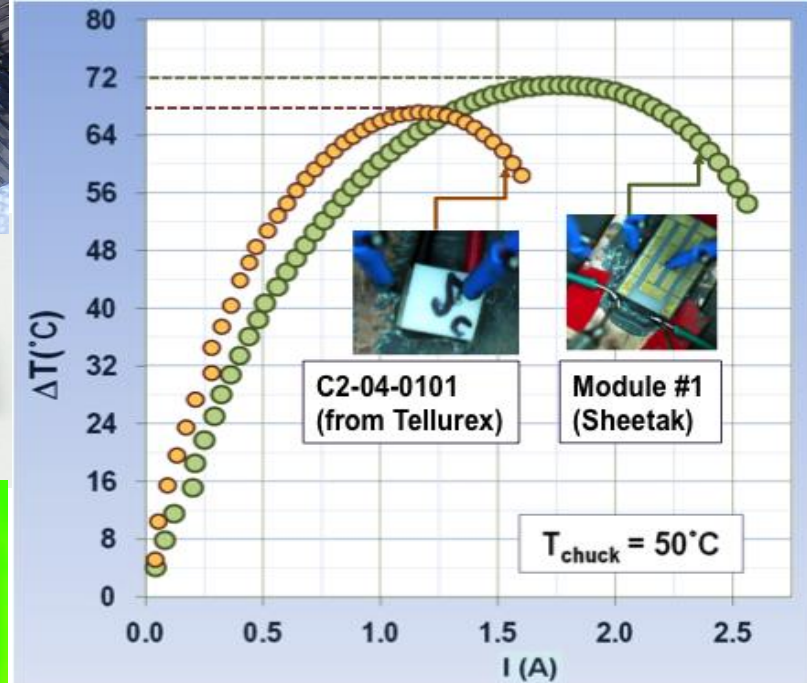
High Performance TE Modules – Thick Film Devices



Barrier Sputtering



- ❖ $\Delta T \sim 80^\circ\text{C}$ for Al-core substrates
- ❖ Significant performance improvements with proprietary nanostructured materials
- ❖ Packaging cost is small for $\sim 1\text{kW}$ heat pumps



Progress and Accomplishments

Accomplishments

- Bottom-mount TE heat pump water heater fabricated and preliminary testing data obtained
- Thin film and new thick film TE fabrication process
- Novel metal-core TE substrate developed (superior to state-of-the-art ceramic substrate)

Challenges

- Slow heating observed by TE heat pump. Risk mitigation involves use of TE heater in conjunction with the resistive heater and better heat sink design
- Significant parasitic temperature losses due to high heat flux in thin film TE. Novel thick film process developed to reduce the parasitic losses

Commercialization Strategy

- Established contacts with Whirlpool and AO Smith in the US and Godrej and Boyce in India
 - AO Smith: World leader in water heaters
 - Whirlpool: Makes store branded heaters
 - Godrej and Boyce: Appliance maker with focus on developing world markets (e.g. India)
 - A.O. Smith is quite cost conscious but Whirlpool and Godrej have stronger interest
- Commercialization focus for the first year:
 - Establish contacts and have introductory discussions
- Commercialization focus for second year:
 - Demonstrate performance of the final prototype with Sheetak TECs (available in the middle of 2nd year)
 - Get into commercial discussions for licensing our system technology and supplying Sheetak TECs

Next Steps and Future Plans

- 8-Engine TE heat pump integration to the water tank
- Development of control algorithm to control TE heat pump and resistive heater operation
- Fabrication of large TE modules on metal-core substrates using Sheetak's thick film process
- Integrated heat pump modules with Sheetak TE and heat sinks
- Demonstration products for engaging potential electric water heater manufacturers (AO Smith, Godrej and Whirlpool)

REFERENCE SLIDES

Project Budget

Project Budget: \$1,149,900.00

Variances: None










Cost to Date: \$1,149,900.00

Additional Funding: N/A

Budget History

11/15/2012– FY2014 (past)		FY2015 (current)		FY2016 – 5/14/2016 (planned)	
DOE	Cost-share	DOE	Cost-share	DOE	Cost-share
\$149,950.00	0	\$499,974.57	0	\$499,975.00	0

Project Plan and Schedule

Project Schedule												
Project Start: May 2014	Completed Work											
Projected End: May 2016	Active Task (in progress work)											
	 Milestone/Deliverable (Originally Planned) Use for missed milestones											
	 Milestone/Deliverable (Actual) Use when met on time											
	FY2014				FY2015				FY2016			
Task	Q1 (May-July)	Q2 (Aug-Oct)	Q3 (Nov-Jan)	Q4 (Feb-Apr)	Q1 (May-Jul)	Q2 (Aug-Oct)	Q3 (Nov-Jan)	Q4 (Feb-Apr)	Q1 (May-Jul)	Q2 (Aug-Oct)	Q3 (Nov-Jan)	
Past Work												
Q1 Product Design												
Q2 Bottom mount TE Heat pump design												
Q2 Packaging of Sheetak's Power TE Heat Pumps												
Q4 Multi-module heat pump hardware												
Current/Future Work												
Q5 Preliminary reliability assessment												
Q6 Water heater product prototype assembly												
Q7 Test to water heater standard							